

Title (en)
Cooking system and method for mounting

Title (de)
Kocheinrichtung und Verfahren zur Montage

Title (fr)
Dispositif de cuisson et procédé de montage

Publication
EP 2775789 B1 20190612 (DE)

Application
EP 14401013 A 20140203

Priority
DE 102013102115 A 20130304

Abstract (en)
[origin: EP2775789A2] The appliance (1) has a heater (2) which is provided for heating a cooking region (31). A sensor device (3) is set to detect physical variable characterizing a state of cooking region. The sensor device is set with a sensor unit, a thermal compensation device and one component. The sensor unit is partially surrounded by component and the component is taken from a group of components that comprises group-magnetic shielding unit, optical shielding element and isolation unit. The sensor unit is arranged partially thermally conductive to thermal compensation device. An independent claim is included for a method for assembling a cooking appliance.

IPC 8 full level
H05B 6/12 (2006.01)

CPC (source: EP)
F24C 7/083 (2013.01); **H05B 1/0266** (2013.01); **H05B 6/062** (2013.01); **H05B 2213/07** (2013.01)

Citation (examination)
• EP 2405712 A1 20120111 - PANASONIC CORP [JP]
• EP 2410815 A1 20120125 - PANASONIC CORP [JP]

Cited by
ES2684128A1; EP3258738A3

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

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